GF28: PCI 3.0

Libraries

Name	Process	Form Factor
RGO_GF28_18V33_SLP_20C_PCI	SLP	Staggered
RGO_GF28_18V33_SLP_40C_PCI	SLP	Inline
RGO_GF28_18V33_HPP_20C_PCI	HPP	Staggered
RGO_GF28_18V33_HPP_40C_PCI	HPP	Inline

Summary

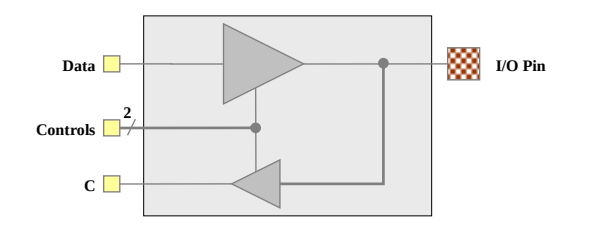
These pads are compatible with PCI Local Bus Specification Revision 3.0 for 3.3V signaling. Cell can be used for both 33MHz and 66MHz operation.

ESD Protection

I/O pads are designed with robust ESD protection for all market segments. Passed:

- 2KV ESD Human Body Model (HBM)
- 200 V ESD Machine Model (MM)
- 500 V ESD Charge Device Model (CDM)

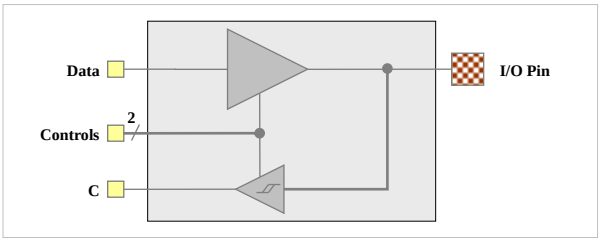
PCx_BI_066_33V_NCW



Description

PCI 3.0 pad without Schmitt trigger.

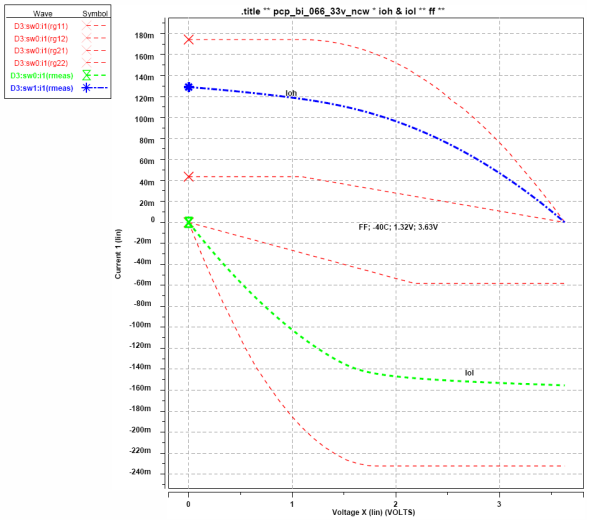
PCx_BI_066_33V_SCW



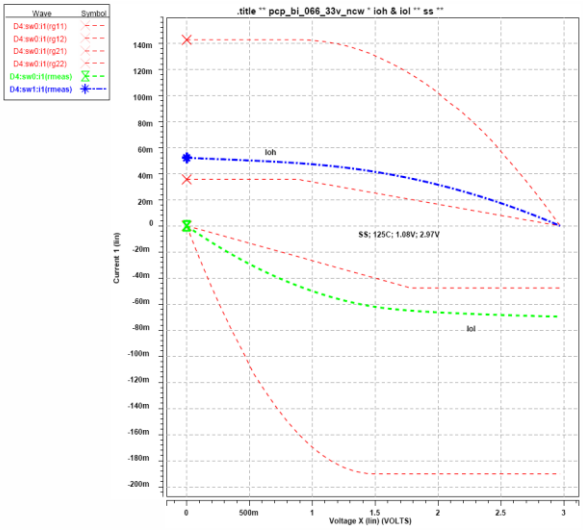
Description

PCI 3.0 pad with Schmitt trigger.

IOH / IOL (FF corner)



IOH / IOL (SS corner)



Recommended operating conditions

	Description	Min	Nom	Max	Units
V_{DVDD}	I/O supply voltage	2.97	3.3	3.63	V
V_{VDD}	Core supply voltage	SLP	0.90	1.0	1.10
			0.99	1.1	1.155
		HPP	0.765	0.85	0.935
			0.81	0.9	0.945
T_J	Junction temperature	-40	25	125	°C
V_{PAD}	Voltage at PAD	0	-	V_{DVDD}	V
V_{IH}	Input logic high	0.5 * V_{DVDD}		V_{DVDD} + 0.3	V
V_{IL}	Input logic low	V_{DVSS} - 0.3		0.3 * V_{DVDD}	V

Characterization Corners

Nom VDD	Model	VDD	DVDD=3.3V	Temp
1.1 (SLP)	FF	+5%	+10%	-40°C
	FF	+5%	+10%	125°C
	TT	nominal	nominal	25°C
	SS	-10%	-10%	-40°C
	SS	-10%	-10%	125°C
1.0 (SLP)	FF	+10%	+10%	-40°C
	FF	+10%	+10%	125°C
	TT	nominal	nominal	25°C
	SS	-10%	-10%	-40°C
	SS	-10%	-10%	125°C
0.9 (HPP)	FF	+5%	+10%	-40°C
	FF	+5%	+10%	125°C
	TT	nominal	nominal	25°C
	SS	-10%	-10%	-40°C
	SS	-10%	-10%	125°C
0.85 (HPP)	FF	+10%	+10%	-40°C
	FF	+10%	+10%	125°C
	TT	nominal	nominal	25°C
	SS	-10%	-10%	-40°C
	SS	-10%	-10%	125°C

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